# 3.3 V / 5 V ECL 2-Input Differential AND/NAND

#### Description

The MC10/100EP05 is a 2-input differential AND/NAND gate. The device is functionally equivalent to the EL05 and LVEL05 devices. With AC performance much faster than the LVEL05 device, the EP05 is ideal for applications requiring the fastest AC performance available.

The 100 Series contains temperature compensation.

#### **Features**

- 220 ps Typical Propagation Delay
- Maximum Frequency > 3 GHz Typical
- PECL Mode Operating Range:
  - $V_{CC} = 3.0 \text{ V}$  to 5.5 V with  $V_{EE} = 0 \text{ V}$
- NECL Mode Operating Range:
  - $\bullet$  V<sub>CC</sub> = 0 V with V<sub>EE</sub> = -3.0 V to -5.5 V
- · Open Input Default State
- · Safety Clamp on Inputs
- Q Output Will Default LOW with Inputs Open or at V<sub>EE</sub>
- · These Devices are Pb-Free, Halogen Free and are RoHS Compliant



#### ON Semiconductor®

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TSSOP-8 DT SUFFIX CASE 948R-02



DFN-8 MN SUFFIX CASE 506AA

#### MARKING DIAGRAMS\*









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H = MC10

A = Assembly Location

K = MC100 5I = MC10 L = Wafer Lot Y = Year

2X = MC100 D = Date Code

W = Work Week

= Date Code • = Pb-Free Package

Application Note AND8002/D.

\*For additional marking information, refer to

(Note: Microdot may be in either location)

#### ORDERING INFORMATION

See detailed ordering and shipping information on page 8 of this data sheet.

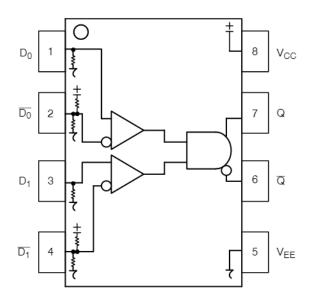


Figure 1. 8-Lead Pinout (Top View) and Logic Diagram

**Table 1. PIN DESCRIPTION** 

Pin	Function
D0*, D1*, <del>D0</del> **, <del>D1</del> **	ECL Data Inputs
Q, Q	ECL Data Outputs
Vcc	Positive Supply
V <sub>EE</sub>	Negative Supply
EP	(DFN-8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

Table 2. TRUTH TABLE

D0	D1	D0	D1	Q	Q
LHH	L H L H	ΙΙΙ	HLHL	L L H	HHHL

Table 3. ATTRIBUTES

Characteristics	Value
Internal Input Pulldown Resistor	75 kΩ
Internal Input Pullup Resistor	37.5 kΩ
ESD Protection Human Body Model Machine Model Charged Device Model	> 4 kV > 200 V > 2 kV
Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)	Pb-Free Pkg
SOIC-8 NB TSSOP-8 DFN-8	Level 1 Level 3 Level 1
Flammability Rating Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count	137 Devices
Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test	

<sup>1.</sup> For additional information, see Application Note AND8003/D.

<sup>\*</sup> Pins will default LOW when left open. \*\* Pins will default to  $V_{\rm CC}/2$  when left open.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	PECL Mode Power Supply	V <sub>EE</sub> = 0 V		6	V
V <sub>EE</sub>	NECL Mode Power Supply	V <sub>CC</sub> = 0 V		-6	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V <sub>EE</sub> = 0 V V <sub>CC</sub> = 0 V	$ \begin{array}{l} V_I \leq V_{CC} \\ V_I \geq V_{EE} \end{array} $	6 -6	V
l <sub>out</sub>	Output Current	Continuous Surge		50 100	mA
TA	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 NB	190 130	°C/W
$\theta_{\text{JC}}$	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8 NB	41 to 44	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8	185 140	°C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44	°C/W
$\theta_{\sf JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN-8	129 84	°C/W
T <sub>sol</sub>	Wave Solder (Pb-Free)	<2 to 3 sec @ 260°C		265	°C
θ <sub>JC</sub>	Thermal Resistance (Junction-to-Case)	(Note 1)	DFN-8	35 to 40	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 5. 10EP DC CHARACTERISTICS, PECL ( $V_{CC} = 3.3 \text{ V}$ ,  $V_{EE} = 0 \text{ V}$  (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	Power Supply Current	20	24	29	20	24	29	20	24	29	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 2)	2165	2290	2415	2230	2355	2480	2290	2415	2540	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	1365	1490	1615	1430	1555	1680	1490	1615	1740	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	2090		2415	2155		2480	2215		2540	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	1365		1690	1460		1755	1490		1815	mV
V <sub>IHCMR</sub>	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	2.0		3.3	2.0		3.3	2.0		3.3	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μА

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V<sub>CC</sub>. V<sub>EE</sub> can vary +0.3 V to -2.2 V. 2. All loading with 50  $\Omega$  to V<sub>CC</sub> 2.0 V.
- V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal.

<sup>1.</sup> JEDEC standard multilayer board - 2S2P (2 signal, 2 power)

Table 6. 10EP DC CHARACTERISTICS, PECL (V<sub>CC</sub> = 5.0 V, V<sub>EE</sub> = 0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current	20	24	29	20	24	29	20	24	29	mA
VoH	Output HIGH Voltage (Note 2)	3865	3990	4115	3930	4055	4180	3990	4115	4240	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	3065	3190	3315	3130	3255	3380	3190	3315	3440	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	3790		4115	3855		4180	3915		4240	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	3065		3390	3130		3455	3190		3515	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	2.0		5.0	2.0		5.0	2.0		5.0	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μΑ
I <sub>IL</sub>	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μА

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +2.0 V to -0.5 V.
- 2. All loading with 50  $\Omega$  to V<sub>CC</sub> 2.0 V.
- 3. VIHCMR min varies 1:1 with VEE, VIHCMR max varies 1:1 with VCC. The VIHCMR range is referenced to the most positive side of the differential input signal.

Table 7. 10EP DC CHARACTERISTICS, NECL ( $V_{CC} = 0 \text{ V}$ ,  $V_{EE} = -5.5 \text{ V}$  to -3.0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	Power Supply Current	20	24	29	20	24	29	20	24	29	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 2)	-1135	-1010	-885	-1070	-945	-820	-1010	-885	-760	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	-1935	-1810	-1685	-1870	-1745	-1620	-1810	-1685	-1560	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	-1210		-885	-1145		-820	-1085		-760	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	-1935		-1610	-1870		-1545	-1810		-1485	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	V <sub>EE</sub>	+2.0	0.0	V <sub>EE</sub>	+2.0	0.0	V <sub>EE</sub>	+2.0	0.0	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μА
I <sub>IL</sub>	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μА

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- Input and output parameters vary 1:1 with V<sub>CC</sub>.
   All loading with 50 Ω to V<sub>CC</sub> 2.0 V.
   V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal.

Table 8. 100EP DC CHARACTERISTICS, PECL (V<sub>CC</sub> = 3.3 V, V<sub>EE</sub> = 0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	Power Supply Current	15	25	32	17	27	36	19	28	38	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 2)	2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	2075		2420	2075		2420	2075		2420	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	1355		1675	1355		1675	1355		1675	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	2.0		3.3	2.0		3.3	2.0		3.3	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μА
IIL	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.3 V to -2.2 V.
- 2. All loading with 50  $\Omega$  to V<sub>CC</sub> 2.0 V.
- 3.  $V_{IHCMR}$  min varies 1:1 with  $V_{EE}$ ,  $V_{IHCMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{IHCMR}$  range is referenced to the most positive side of the differential input signal.

Table 9. 100EP DC CHARACTERISTICS, PECL (V<sub>CC</sub> = 5.0 V, V<sub>EE</sub> = 0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I <sub>EE</sub>	Power Supply Current	15	25	32	17	27	36	19	28	38	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 2)	3855	3980	4105	3855	3980	4105	3855	3980	4105	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	3055	3180	3305	3055	3180	3305	3055	3180	3305	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	3775		4120	3775		4120	3775		4120	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	3055		3375	3055		3375	3055		3375	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	2.0		5.0	2.0		5.0	2.0		5.0	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μА
I <sub>IL</sub>	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μΑ

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +2.0 V to -0.5 V.
- All loading with 50 Ω to V<sub>CC</sub> 2.0 V.
   V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal.

Table 10. 100EP DC CHARACTERISTICS, NECL ( $V_{CC} = 0 \text{ V}$ ,  $V_{EE} = -5.5 \text{ V}$  to -3.0 V (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current	15	25	32	17	27	36	19	28	38	mA
V <sub>OH</sub>	Output HIGH Voltage (Note 2)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	-1945	-1820	-1695	-1945	-1820	-1695	-1945	-1820	-1695	mV
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	-1225		-880	-1225		-880	-1225		-880	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	-1945		-1625	-1945		-1625	-1945		-1625	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	V <sub>EE</sub>	+2.0	0.0	V <sub>EE</sub>	+2.0	0.0	V <sub>EE</sub>	+2.0	0.0	V
I <sub>IH</sub>	Input HIGH Current			150			150			150	μА
IIL	Input LOW Current D D	0.5 -150			0.5 -150			0.5 -150			μА

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 1. Input and output parameters vary 1:1 with V<sub>CC</sub>.
- 2. All loading with 50  $\Omega$  to V $_{CC}$  2.0 V.
- V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, V<sub>IHCMR</sub> max varies 1:1 with V<sub>CC</sub>. The V<sub>IHCMR</sub> range is referenced to the most positive side of the differential input signal.

Table 11. AC CHARACTERISTICS ( $V_{CC} = 0 \text{ V}$ ;  $V_{EE} = -3.0 \text{ V}$  to -5.5 V or  $V_{CC} = 3.0 \text{ V}$  to 5.5 V;  $V_{EE} = 0 \text{ V}$  (Note 1))

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Frequency (Figure 2)		> 3			> 3			> 3		GHz
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay to Output Differential	160	210	260	170	220	270	210	260	320	ps
t <sub>JITTER</sub>	Random Clock Jitter (Figure 2)		0.2	< 1		0.2	< 1		0.2	1.5	ps
V <sub>PP</sub>	Input Voltage Swing (Differential Configuration)	150	800	1200	150	800	1200	150	800	1200	mV
t <sub>r</sub> t <sub>f</sub>	Output Rise/Fall Times Q (20% - 80%)	70	120	170	80	130	180	100	150	200	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

1. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50  $\Omega$  to V<sub>CC</sub> – 2.0 V.

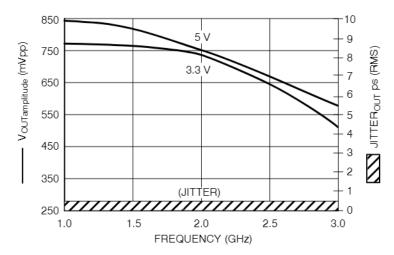


Figure 2.  $F_{max}/Jitter @ 25^{\circ}C$ 

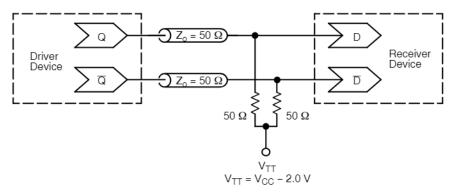


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note <u>AND8020/D</u> – Termination of ECL Logic Devices.)

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
MC10EP05DG	SOIC-8 NB (Pb-Free)	98 Units / Rail
MC10EP05DR2G	SOIC-8 NB (Pb-Free)	2500 / Tape & Reel
MC10EP05DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC10EP05DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100EP05DG	SOIC-8 NB (Pb-Free)	98 Units / Rail
MC100EP05DR2G	SOIC-8 NB (Pb-Free)	2500 / Tape & Reel
MC100EP05DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100EP05DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100EP05MNR4G	DFN-8 (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <a href="https://example.com/BRD8011/D">BRD8011/D</a>.

#### **Resource Reference of Application Notes**

AN1405/D - ECL Clock Distribution Techniques

AN1406/D - Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

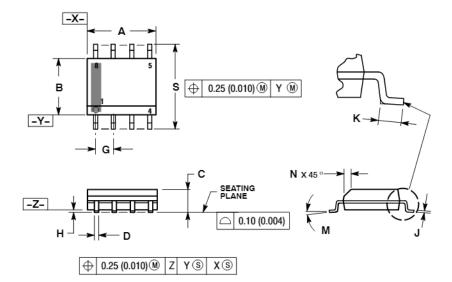
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

#### PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 ISSUE AK

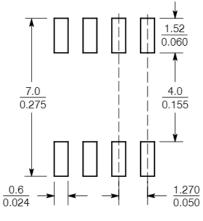


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- ANSI Y14.5M, 1982.
  CONTROLLING DIMENSION: MILLIMETER.
  DIMENSION A AND B DO NOT INCLUDE
  MOLD PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 (0.006)
  BED SIDE.
- 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006)
  PER SIDE.
  5. DIMENSION D DOES NOT INCLUDE DAMBAR
  PROTRUSION. ALLOWABLE DAMBAR
  PROTRUSION SHALL BE 0.127 (0.005) TOTAL
  IN EXCESS OF THE D DIMENSION AT
  MAXIMUM MATERIAL CONDITION.
  6. 751-01 THRU 751-06 ARE OBSOLETE. NEW
  STANDARD IS 751-07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

#### SOLDERING FOOTPRINT\*

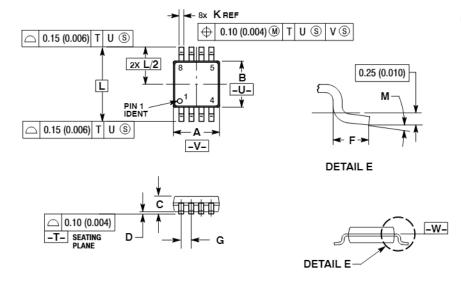


SCALE 6:1

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

TSSOP-8 CASE 948R-02 ISSUE A



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI
  - Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER.
- 2. OOVTHOCHING DIMERSON, MICLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH. OR GATE BURRS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.

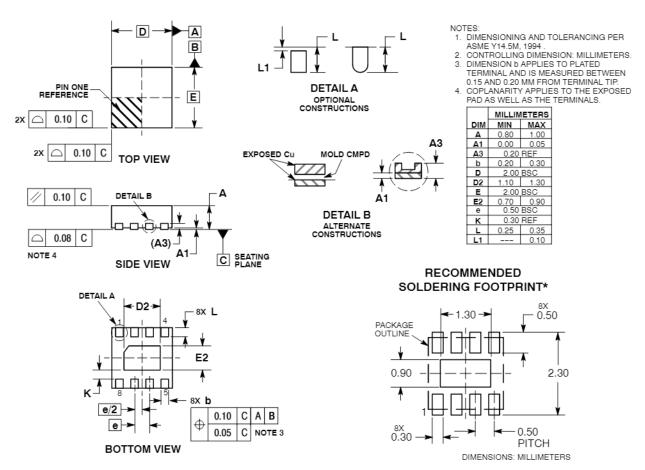
  4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
  5. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.

  6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
С	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
М	0.0	6 °	0.0	60

#### PACKAGE DIMENSIONS

DFN-8 2x2, 0.5P CASE 506AA ISSUE F



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, <u>SOLDERRM/D</u>.

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